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Impact of high temperature H$_2$ pre-treatment on Pt-AlGaN/GaN HEMT sensor for H$_2$S detection

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Highlights:

- A H$_2$ gas flow pre-treatment at high temperature is utilized for Pt-AlGaN/GaN HEMT H$_2$S sensors
- The detection concentration range of H$_2$S is extended after pre-treatment
- The linearity of Pt-HEMT sensors is improved after pre-treatment
- The mechanism behind pre-treatment is discussed and characterized

Abstract:

In this paper, a method to extend the detection range of hydrogen sulfide (H$_2$S) gas sensor is demonstrated. The sensor is based on AlGaN/GaN high electron mobility transistors (HEMTs) with Pt gate. It is observed that the as-fabricated devices exhibited sensing signal saturation at 30 ppm H$_2$S exposure in dry air. A pre-treatment using H$_2$ pulses in dry air ambient at 250 °C was applied to extend the detection range of the sensor. The H$_2$ treated H$_2$S gas sensor was able to detect a higher
H$_2$S concentration up to 90 ppm at 250 °C without complete saturation.

**Key words:** AlGaN/GaN; Pt; HEMT; H$_2$S; Gas Sensor

1. **Introduction**

H$_2$S is colorless gas with the foul smell of rotten eggs. It can be emitted by many industrial activities, such as petroleum refining or paper mills [1]. Besides, it is a broad-spectrum poison and can severely affect the nervous system. Only 20 ppm H$_2$S is the acceptable ceiling concentration established by the Occupational Safety and Health Administration (OSHA) [2]. For 100-150 ppm H$_2$S, it can paralyze the olfactory nerve, and then the sense of smell will disappear [1]. Therefore, it is necessary to detect H$_2$S within low tens up to at least 100 ppm.

There are many ways to detect H$_2$S, such as metal-oxide semiconductor (MOS) [1, 3], electrochemical [4], Schottky diode [5] and field effect transistor sensors [6, 7]. Because industrial activity is one of the largest sources of H$_2$S, harsh environments like high temperature should be taken into consideration. Due to the wide bandgap, high chemical stability and corrosion resistance, the compound semiconductors like GaN [8, 9] and SiC [10, 11] have gained many interests. Compared with Schottky diode sensors, the transistor-based sensors usually have a larger sensing current and a higher signal-to-noise ratio. Especially for AlGaN/GaN based HEMT [12, 13], due to the presence of two-dimensional electron gas (2DEG), the response current is even larger than mA level.

Previously, Darmastuti et al. had fabricated a H$_2$S sensor based on SiC field effect transistor (FET) with Pt or Ir gate [10]. The device exhibited saturation at a low concentration of approximately 10 ppm, which is similar to our as-fabricated sensors. No pre-treatment was reported for their sensors. It was also demonstrated that the as-fabricated Pt-SiC MOS sensors showed little or no H$_2$ gas response [14]. In order to activate sensors, alternated exposures of 1% O$_2$ in N$_2$ (5 min) and 10% H$_2$ in N$_2$ (3 min) for 7 h at 610 °C were once applied [14].

In this work, we report on the H$_2$ related pre-treatment for H$_2$S gas sensors based on the AlGaN/GaN HEMT. It clearly shows the effective extension of H$_2$S detection range.

2. **Experimental**
Fig. 1 (a) shows the cross-sectional view of our HEMT-sensors. The devices were fabricated on 2-inch sapphire wafers with epitaxial stacks grown by MOCVD. The epitaxial stacks started with a nucleation layer in order to reduce the lattice mismatch. Then it was followed by a 1.8 μm GaN buffer layer, a 1 nm AlN interlayer, an unintentionally doped 21 nm Al0.26Ga0.74N barrier layer and a 1 nm GaN capping layer. The mesa etching was performed by BCl3/Cl2 plasma to isolate devices. Then a Ti/Al/Ti/Au (20/110/40/50 nm) stack was deposited on source/drain by e-beam evaporation and patterned by lift-off method. Annealing at 870 °C for 47 s in N2 ambient was performed to form Ohmic contacts. Next, the sensing gate electrode was formed by e-beam evaporation of a 10 nm Pt layer. Gate pattern was also defined by lift-off process. The bi-layer of 30/300 nm Ti/Au was also fabricated by lift-off process as wire bonding metal. The devices were passivated by 500 nm SiNx using PECVD. Finally, Pt gate area was opened to detect the gas. The gate dimension exposed to gas was 40 μm × 400 μm (length × width) and the spacing between gate and source/drain was 6 μm [15].

The as-fabricated sensors were annealed at 150 °C in dry air for 48 hours to test sensors’ thermal stability. The sensors with no performance degradation were used for the formal measurement. A commercial gas mixing system was employed for H2S sensing and H2 pre-treatment. A stable gas flow at a rate of 310 sccm was continuously introduced into a 1.8 L chamber. H2S or H2 gas in dry synthetic air background with different concentration was used. The humidity in chamber was kept at 0% RH for all the measurements to inhibit moisture influence. For H2 pre-treatment, the samples were exposed to alternated gas flows of dry air (50 min) and H2 (20 min) for 6 hours at 250 °C. The concentration of H2 was increased with each exposure from 100 ppm to 900 ppm at 300 ppm increment. The electrical signals were measured by a pair of Keithley 2450 source meters with the measurement temperature varying from room temperature to 300 °C. After each measurement cycle, the sensors were reset under room ambient conditions for at least 12 hours. Atomic force microscopy (AFM) was utilized to analyze the Pt gate surface morphology before and after H2 pre-treatment.

3. Results and discussion

3.1 As-fabricated sensors
Our previous studies have shown that the sensor can operate from 150 to 250 °C, and the best performance is obtained at an operation temperature of 250 °C [16]. Fig. 1 (b) shows the output curves of a HEMT sensor exposed to 15 ppm H₂S gas at 250 °C. Obviously, it shows linear and saturation regions with a pinch-off voltage of -3 V (gate-source voltage, V_{GS}). It is a normally-on device due to the 2DEG. When exposed to H₂S gas, the source-drain current I_{DS} increases even at a low concentration of 15 ppm, as shown in Fig. 1(b). The detection mechanism is related with the reaction between gas and catalytic metal Pt. After H₂S is adsorbed on Pt film, the S-H bond is then divided by Pt, resulting in the production of H atom or molecule [5]. Finally, the S atom can react with O₂ to form volatile SO₂ and the H atom can form a dipole layer. The dipole layer can affect the Schottky barrier height between Pt and GaN. Consequently, the threshold voltage and the drain current are altered.

Fig. 2 (a) shows the transient response curves for different H₂S concentrations at 250 °C using a fresh sensor without H₂ pre-treatment. The transient response curves were measured at fixed voltages (V_{GS}=0 V and V_{DS}=5 V). The drain current (I_{DS}) was recorded with a 3s interval. Clearly, I_{DS} is saturated at a low concentration of 30 ppm. With a higher gas concentration, the H₂S atoms will cover larger area of Pt surface. Then the output signal intensity increases. But there is a limit for coverage, which may result in saturation of signal intensity. This phenomenon is similar to other studies based on Pt-SiC field effect transistor [10].

### 3.2 H₂ pre-treated sensors

Fig. 2 (b) shows the transient response curves for the H₂ pre-treated sensors at 250 °C. The different H₂S concentration is clearly distinguished.

To compare the detection range more quantitatively, the gas response is calculated by

\[
S(\%) = \frac{\Delta I_{DS}}{I_{DS,air}} \times 100\%.
\]

where \( \Delta I_{DS} = I_{DS,H2S} - I_{DS,air} \) is the drain current variation between H₂S and air ambient. Fig. 3 (a) shows the gas response to H₂S for sensors with and without H₂ pre-treatment. Without H₂ pre-treatment, the gas response is nearly unchanged for different H₂S concentration. While, with H₂ pre-treatment it’s almost linear. The large difference indicates that the H₂ pre-treatment can effectively improve sensor performance by extending its detection range.
Before sensing H$_2$S, the influence of H$_2$ pre-treatment on sensors is summarized in Fig 3(b) - (d). As shown in Fig. 3 (b), the H$_2$ pre-treatment obviously makes the drain current become smaller. The expression of drain current in saturation region is,

$$I_{DSS} = \frac{\mu C_b W_g}{2l_g} (V_{GS} - V_{TH})^2,$$

where $\mu$ is the 2DEG mobility, $W_g/l_g$ is the ratio of gate width to length, $C_b$ is the sum of capacitance contributions from each layer between the gate metal and 2DEG (1/$C_b = 1/C_{GaN} + 1/C_{AlGaN} + 1/C_{AlN} + 1/C_{2DEG}$). Threshold voltage ($V_{TH}$) in this work is extracted from $\sqrt{I_{DS}} - V_{GS}$ curve biased in the saturation region [17]. The $V_{TH}$ shift can be observed in Fig. 3 (c), which shows a positive shift and results in $I_{DS}$ and transconductance $g_m$ reduction. Fig. 3 (d) is the extracted $I_{DS}$ shift and $V_{TH}$ shift at different measurement temperature. At a higher measurement temperature, the $V_{TH}$ shift decreases and the $I_{DS}$ shift is smaller too. The expression of $V_{TH}$ for an AlGaN/GaN HEMT is [18].

$$V_{TH} = \Phi_b - \frac{\Delta E_c}{q} - \frac{q n_s}{C_b},$$

where $\Phi_b$ is the Schottky barrier height, $\Delta E_c$ is the conduction band discontinuity, $q$ is the electron charge and $n_s$ is the sheet charge carrier density. The Schottky barrier height is dependent on the work function ($\Phi_m$) of the gate metal and the semiconductor electron affinity ($\chi_s$), i.e., $\Phi_b = \Phi_m - \chi_s$. Therefore, we believe the shift of $V_{TH}$ should be related to the work function variation of the gate metal.

3.3 Explanation

For the $V_{TH}$ positive shift after H$_2$ pre-treatment, there are three possible reported mechanisms [19]: a) the adsorbed H atoms give rise to a dipole layer; b) the existence of slow H trapping sites; and c) the lattice expansion due to H induced stress. The dipole layer is reversible and decreases the $V_{TH}$ [20-22]. The existence of slow H trapping sites is also called Hydrogen-Induced Drift (HID), which is related to the metal-insulator interface [19, 23]. It is not temporary but it can decrease the $V_{TH}$. According to previous studies [19, 24], the stress induced by H can change the metal lattice parameters. Besides, it can even loosen contact between metal and substrate [24]. However, we didn’t find any difference of sensor after H$_2$ pre-treatment by microscope. The AFM measurements shown in Fig. 4 also clearly indicate little change on Pt film. So, a), b) and c) cannot explain our
A new mechanism is proposed in this paper. Fig. 5 (a) and (b) show the H existence status in Pt gate for sensors with and without H$_2$ pre-treatment. There will be two statuses of H atoms within Pt film. One is trapped by the body defects in the Pt grains, losing its electron and existing as fixed positive H$^+$ ions. Then the induced negative charges will accumulate on Pt film surface as shown in Fig. 5(b). These negative charges will increase the work function of Pt film, resulting in the $V_{TH}$ positive shift and $I_{DS}$ reduction as mentioned in section 3.2. Since these H$^+$ ions within Pt grains are fixed, these induced negative charges on Pt film surface are also stable. So there is a larger $V_{TH}$ for these transistors with H$_2$ pre-treatment as shown in Fig. 3(b). The other status of H is related with absorption by Pt surface defects [25], such as surface clusters, steps and grain boundaries. Once absorbed, H atoms will show positive polarity due to a weaker electronegativity comparing with Pt. Thus, a dipole layer may form around the Pt film surface and grain boundaries as shown in Fig. 5(c) [19]. These dipole layers will equivalently lower the Pt film work function, which will reduce the $V_{TH}$, as calculated in equation (3). However, these absorbed H atoms are not stable, they can diffuse out into the atmosphere when the sensed H$_2$ concentration is lower.

Since there are fixed H$^+$ ions within the Pt grains after H$_2$ pre-treatment, the induced negative charges on the Pt film surface and interface will stably exist there. While, the adsorbed H atoms on the Pt top surface will show positive polarity. Thus, the induced negative charges will attract these adsorbed H atoms. Consequently, on the Pt top surface the entrance for the adsorbed H atoms’ diffusion into the Pt grain boundaries and interface of Pt/GaN will be partly blocked. The H atoms diffusion velocity at these entrances will be lowered. Hence, with the same sensing condition the amount of H atoms which can finally diffuse into the interface of Pt/GaN will decrease for the same H$_2$S concentration. So even for 90 ppm H$_2$S the $I_{DS}$ is still not saturated for the sensor with H$_2$ pre-treatment. As seen in Fig. 2(b), the $I_{DS}$ for 90 ppm H$_2$S is less than that for 30 ppm H$_2$S but without H$_2$ pre-treatment as shown in Fig. 2(a). Thus, the sensor detection range is extended.

Besides, Fig. 6 shows the transient response curves for samples pre-treated with H$_2$ at 250 ºC. Only after exposure to 900 ppm H$_2$, the $I_{DS}$ in dry air obviously degrades. It means that the positive H$^+$ ions form within the Pt grains, which indicates that it is not easy to form these diffusion induced H$^+$ ions. A higher temperature and a higher H$_2$ concentration are preferred to activate and accelerate
the diffusion process within the grains. Once these H\(^+\) ions form they will be much more stable than those adsorbed H atoms at surface or interface. It also implies the H\(^+\) ions formation process can be ignored when the H\(_2\) concentration is less than 100 ppm.

4. Conclusion:

In this paper, it is demonstrated that the Pt-AlGaN/GaN HEMT can detect H\(_2\)S at 250 °C. However, the as-fabricated sensors exhibit saturation for low H\(_2\)S concentrations. A high temperature H\(_2\) pre-treatment is proposed and successfully applied to extend the concentration detection range. The mechanism is believed to be correlated with the interaction between Pt film and H\(_2\), which may introduce stable H\(^+\) ions within Pt grains and result in the \(V_{TH}\) positive shift. The negative charges induced by these H\(^+\) ions at the Pt top surface will attract the adsorbed H atoms with positive polarity. This will reduce the diffusion velocity of these adsorbed H atoms, finally decreasing the amount of H related dipoles at Pt/GaN interface. Thus a higher H\(_2\)S concentration is required to reach the same saturation level of the dipoles at Pt/GaN interface, which equivalently increases the H\(_2\)S concentration detection range.

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Figure captions

Fig 1. (a) The cross-sectional diagram of HEMT-sensor in this work. (b) The output curves of a fresh sensor exposed to air and 15 ppm H2S at 250 °C without H2 pre-treatment.

Fig 2. (a) The transient response curves for H2S at 250 °C without H2 pre-treatment. (b) The transient response curves for H2S at 250 °C with H2 pre-treatment.

Fig 3. (a) Gas responses for sensors with and without H2 pre-treatment measured at 250 °C. (b) Output curves for sensors with and without H2 pre-treatment measured at 250 °C. (c) Transfer and gm curves for sensors with and without H2 pre-treatment measured at 250 °C (VDS=7 V). (d) With H2 pre-treatment the measurement temperature influence on Ins shift (Ids,shift, VGS=0 V, VDS=5 V) and threshold voltage shift (VTH,shift).

Fig 4. AFM image for Pt film surface (a) without and (b) with H2 pre-treatment at 250 °C.
Fig 5. The H existence status in Pt gate for sensor (a) without and (b) with H₂ pre-treatment. The H existence status in Pt gate after sensing H₂S for sensor (c) without H₂ pre-treatment and (d) with H₂ pre-treatment.

Fig 6. The transient response curve for samples treated with H₂ at 250 °C.